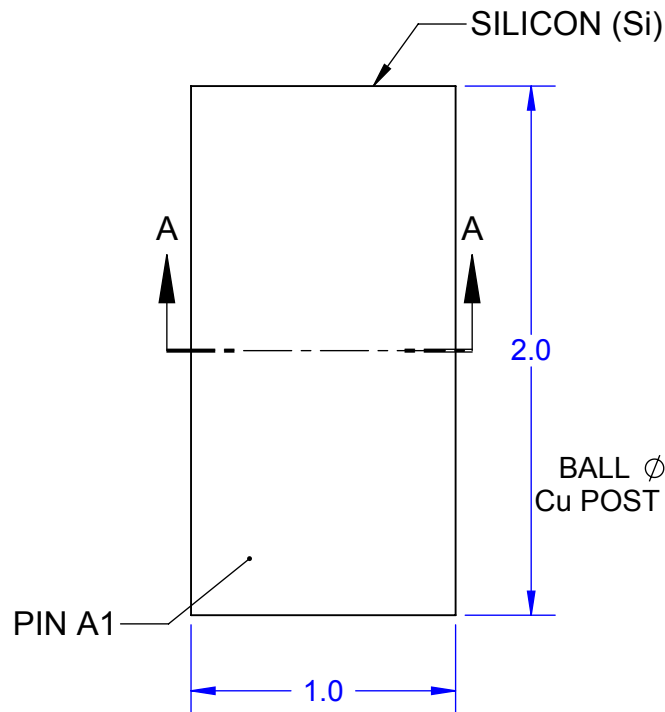
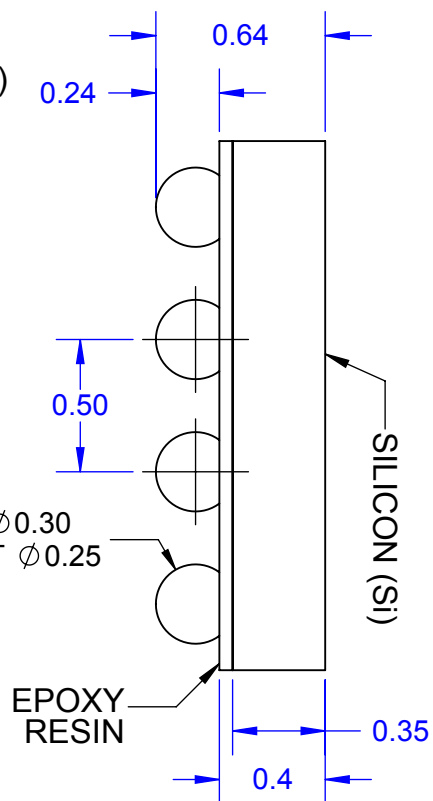


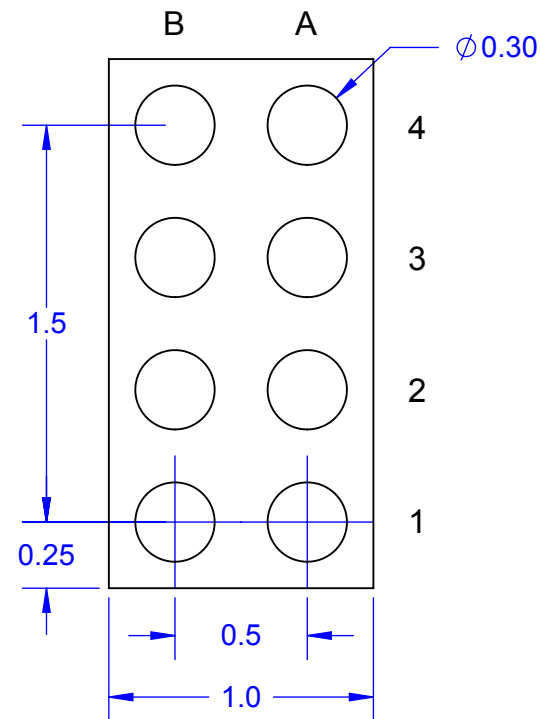
TOP VIEW



SIDE VIEW

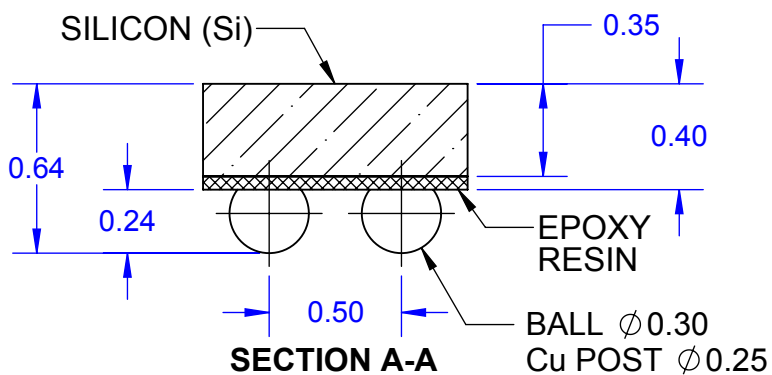


BALL VIEW



Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY:
STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER: 0.25mm.
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) DAISY CHAIN PATTERN (SEE PAGE 2).

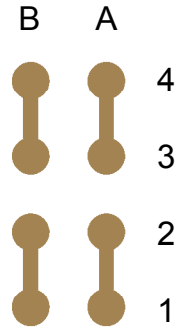


PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP8T.5C-DC024D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES

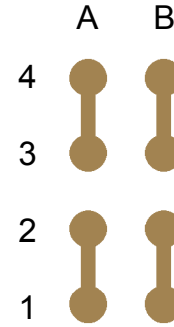
APPROVALS	DATE	TopLine®		
DRAWN T.Au	12/1/13			
ENG M. Hart	12/1/13	TITLE WLP8T.5C-DC024D 8-BALL P=0.5mm		
MFG		SCALE	SIZE	DRAWING NO.
QA		35:1	A	552480
CUST				REV A
REVISED		DO NOT SCALE DRAWING		SHEET 1 OF 2

DAISY CHAIN PATTERN

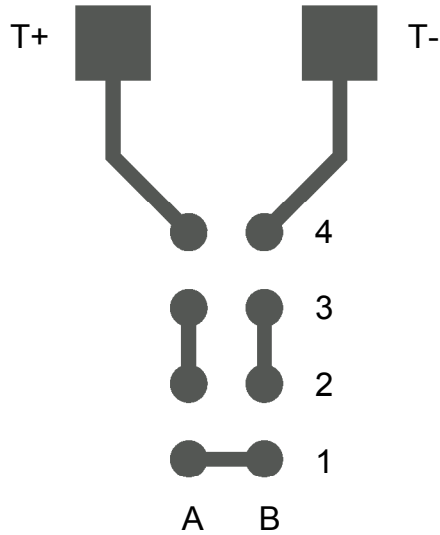
BALL VIEW



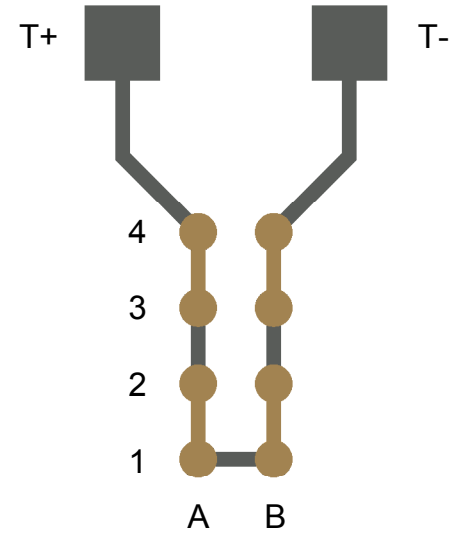
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.25mm (9.8mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9mil).



TITLE			
WLP8T.5C-DC024D 8-BALL P=0.5mm			
SCALE	SIZE	DRAWING NO.	REV
20:1	A	552480	A
DO NOT SCALE DRAWING			SHEET 2 OF 2